

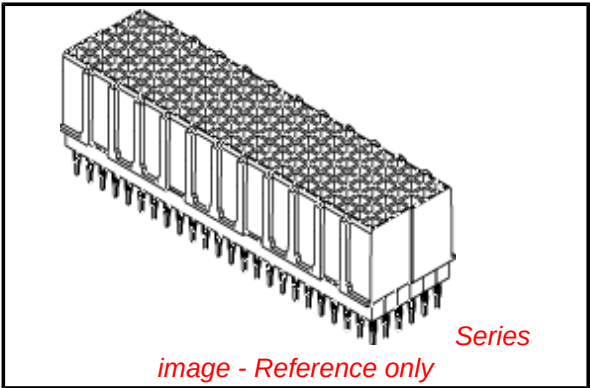
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Part Number: [0737801144](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 14.00mm (.551"), Pin Length 3.00mm (.118"), Solder Tail

Documents:
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73780-999 \(PDF\)](#)

General	
Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	hdm
Product Name	HDM®
Style	N/A

Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.118 In
PC Tail Length (mm)	3.00 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.063 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73780Series](#)

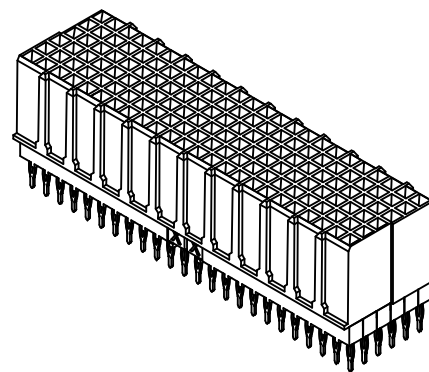
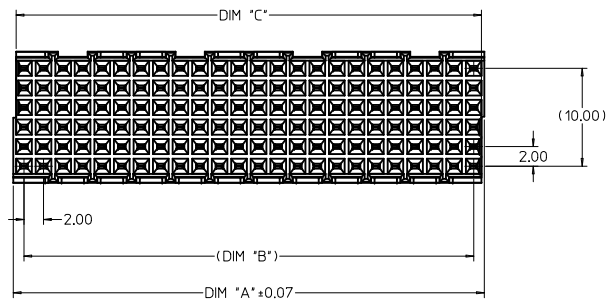
Mates With
HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	15A, 1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Product Specification	PS-73780-999
Sales Drawing	SD-73780-004

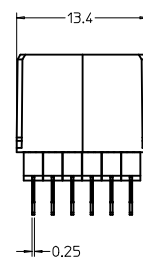
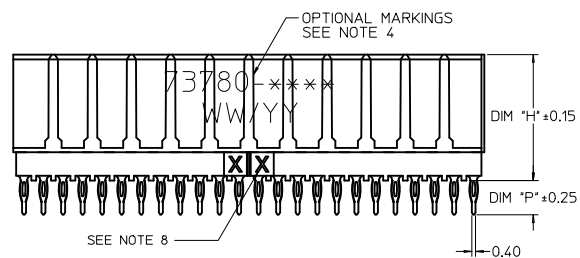
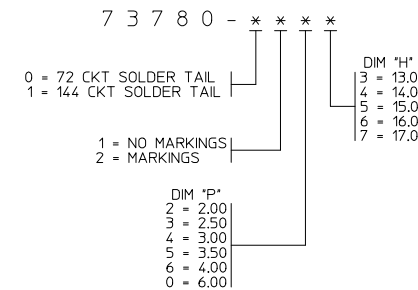
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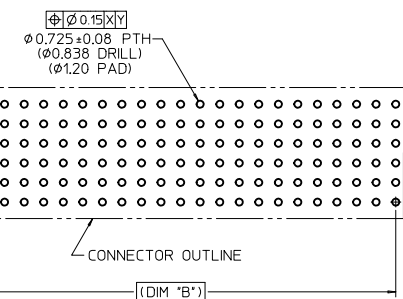


MATERIAL NUMBER ASSIGNMENT



NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, .76 MICROMETER MINIMUM THICKNESS, SELECTIVE TIN (Sn), 2.50 MINIMUM THICKNESS ON SOLDER TAILS, NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. MARKINGS SHOWN FOR REFERENCE ONLY. SEE MATERIAL NUMBER ASSIGNMENT DIAGRAM FOR CORRECT NUMBER. MARKINGS TO INCLUDE MATERIAL NUMBER AND DATE CODE AND CAN BE LOCATED ANYWHERE ON PART, IN ANY ORIENTATION.
5. 73780-***7 AND -***0* PARTS TO BE PACKAGED IN TUBES PER PK-70873-0872. ALL OTHER PARTS TO BE PACKAGED IN TUBES PER PK-70873-0900.
6. 144-CIRCUIT HDM DAUGHTERCARD STACKING MODULE WITH PRESS-FIT TAILS SHOWN FOR ILLUSTRATION PURPOSES ONLY.
7. TRUE POSITION OF PC TAILS IS INSPECTED USING GAUGE NUMBER 73727-0014.
8. MARKINGS MAY BE ORIENTED TO EITHER SIDE OF CONNECTOR.



PCB LAYOUT: COMPONENT SIDE

73780-1***	144	48.17	46.00	47.6
73780-0***	72	24.17	22.00	23.6
MATERIAL NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"

UPDATE TO S.T. ONLY IEC NO: UCP2010-1860 DRAWN: J. MELTON 2010/01/22 CHECKED: S. DANIELLEY 05/07/08 APPROVED: S. MILLER 2010/02/08 DESCRIPTION:	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0		GENERAL TOLERANCES (UNLESS SPECIFIED) 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.05 ± --- 1 PLACE ± 0.10 ± --- ANGULAR ± 2 °		DIMENSION STYLE MM ONLY DRAWN BY: MIBARRA DATE: 05/07/08 CHECKED BY: BSMART DATE: 05/07/08 APPROVED BY: S. MILLER DATE: 2010/02/08		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SALES ASSEMBLY, HDM DAUGHTERCARD STACKING MODULE, SOLDER TAIL		MOLEX INCORPORATED		SD-73780-004		SHEET NO. 1 OF 1
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SEE TABLE		DOCUMENT NO.		MOLEX		MOLEX
	SIZE D		SIZE D		SIZE D		SIZE D		SIZE D